

■ **⚠ Caution (Storage and Operating Conditions)**

This product is designed for application in an ordinary environment (normal room temperature, humidity and atmospheric pressure). Do not use under the following conditions because all of these factors can deteriorate the product characteristics or cause failures and burn-out.

1. Corrosive gas or deoxidizing gas (Chlorine gas, Hydrogen sulfide gas, Ammonia gas, Sulfuric acid gas, Nitric oxide gas, etc.)

2. Volatile or flammable gas
3. Dusty conditions
4. Under vacuum, or under high or low pressure
5. Wet or humid locations
6. Places with salt water, oils, chemical liquids or organic solvents
7. Strong vibrations
8. Other places where similar hazardous conditions exist

■ **⚠ Caution (Others)**

Be sure to provide an appropriate fail-safe function on your product to prevent secondary damages that may be caused by the abnormal function or the failure of our product.

■ **Notice (Storage and Operating Conditions)**

To keep solderability of product from declining, the following storage condition is recommended.

1. Storage Condition: Temperature -10 to +40°C
Humidity less than 75%RH (not dewing condition)
2. Storage Term: Use this product within 6 months after delivery by first-in and first-out stocking system.

3. Handling after Unpacking: After unpacking, reseal product promptly or store it in a sealed container with a drying agent.
4. Storage Place: Do not store this product in corrosive gas (Sulfuric acid gas, Chlorine gas, etc.) or in direct sunlight.

■ **Notice (Rating)**

Use this product within the specified temperature range. Higher temperature may cause deterioration of the characteristics or the material quality of this product.

■ **Notice (Soldering and Mounting)**

Please notice as shown below when you mount this product.

1. Please perform soldering on a condition not melt the solder in resin head (more than 25mm in full length of the product). If you melt the solder in resin head, it has possibility that the break of wire and short.
2. Do not touch the resin head directly by solder iron. It may cause the melt of solder in resin head.

3. When additional processing is carried out to this product (such as bonding, the resin molding, and the resin courting, etc.), please do a quality rating enough by a real machine and use it after confirming it is unquestionable. Please talk to us if you have concern matter, like process it under the high temperature and the high pressure. (For example, exposed to high-temperature and high-pressure environment as mold sealing with injection molding.)

■ **Notice (Handling)**

1. The ceramic element of this product is fragile, and care must be taken not to load an excessive press-force or not to give a shock at handling. Such forces may cause cracking or chipping. Especially, under high temperature environment, there is a possibility that epoxy resin will become soft. When you set up processing environment, please examine the processing method after evaluate the quality of this product.

2. Do not apply an excessive force to the lead. Otherwise, it may cause junction between lead and element to break or crack. Holding element by side lead wire is recommended when lead wire is bent or cut. Handle the lead with care, there is a possibility that a crack may go into the polyurethane insulated coat when bending the lead.